

DO NOT ENTER MP 5/06

CHIP-PACKAGING WITH BONDING OPTIONS HAVING A PLURALITY OF PACKAGE SUBSTRATES

Appl. No.

10/709,427

Confirmation No. 3426

Applicant

Cheng-Yen Huang

Filed

May 5, 2004

TC/A.U.

2822

Examiner

Prenty, Mark V

Docket No.

FTCP0036USA0

Customer No.

27765

Commissioner for Patents

P.O. Box 1450

Alexandria VA 22313-1450

AMENDMENT

5 Sir:

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In response to the Office action of March 31, 2006, please amend the above-identified application as follows:

Amendments to the Specification begin on page 2 of this paper.

Amendments to the Claims are reflected in the listing of claims which begins on page 8 of this paper.

Amendments to the Drawings begin on page 10 of this paper and include two new sheets.

Remarks/Arguments begin on page 11 of this paper.

An Appendix including amended drawing figures is attached following page 14 of this paper.